Not	tifica	tion Number:	20221	018	003.0	Notificatio	n Date	:	Oct	tober 1	9, 2022	
Titl	e:	Datasheet for C	Dx4HC73	, CD	074HCT73, C	CDx4HC112,	CDx4H	CT1	12, C	Dx4HC6	88,	
		CDx4HCT688							-	O	C	
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		Type:			Decign				Nofor	Burne C	`it o	
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\exists	Assembly Process		Data Sheet Part number change				Wafer Bump Material Wafer Bump Process					
Assembly MaterialsMechanical Specification		Test Site				Wafer Fab Site						
Packing/Shipping/Labeling			Test Process				Wafer Fab Materials					
								1	Wafer Fab Process			
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		tion of Change: Instruments Incorpo	unter d'in					L :C:				
The	e proc e follo	duct datasheet(s) owing change histo xas	is being (upda	ated as sum	marized be	ow.					70
_	ĪN	STRUMENTS				SC	HS134G – F	EBR	UARY 199	8 – REVISE	B, CD74HCT)22
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•	Incre	eased R0JA for packa	ges: D (86	to 1	38.7); N (80 to	o 91)						4
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<u>c</u> •	Incr	eased RθJA for packa	-			CD54HC6	22) 34 to 88.4 38, CD74H	-); P	W (108 88, CD5	to 137.5 4HCT688	Pa 5)	022 ge 4
•	Incr	eased RθJA for packa EXAS NSTRUMENTS	ages: D (73	3 to 1	17.2); N (67 to	CD54HC6	22) 44 to 88.4 88, CD74 HS196E – SI	-); P	W (108 88, CD5	to 137.5 4HCT688	Pa 5) , CD74HCT (ED OCTOBER 2	022 ge . 4
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Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this notification:

None.								
Product Affected:								
CD74HC112E	CD74HC112PWT	CD74HC73E	CD74HCT688EE4					
CD74HC112M96	CD74HC688E	CD74HC73M	CD74HCT688M					
CD74HC112MT	CD74HC688M	CD74HC73M96	CD74HCT688M96					
CD74HC112NSR	CD74HC688M96	CD74HC73MT	CD74HCT73E					
CD74HC112PW	CD74HC688NSR	CD74HCT112E	CD74HCT73M					
CD74HC112PWR	CD74HC688PWR	CD74HCT688E	CD74HCT73M96					
CD74HC112PWRE4	CD74HC688PWT							

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